

MA3X740 (MA740)

Silicon epitaxial planar type

For super high speed switching

For small current rectification

■ Features

- Two MA3X721 (MA721) is contained in one package (series connection)
- $I_{F(AV)} = 200$ mA (per single diode) rectification is possible
- Mini type 3-pin package

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|--|-----------|-------------|------------------|
| Reverse voltage (DC) | V_R | 30 | V |
| Repetitive peak reverse-voltage | V_{RRM} | 30 | V |
| Average forward current | Single | 200 | mA |
| | Series *1 | 130 | |
| Peak forward current | Single | 300 | mA |
| | Series *1 | 220 | |
| Non-repetitive peak forward-surge-current *2 | Single | 1 | A |
| | Series *1 | 0.7 | |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *1: Value per chip

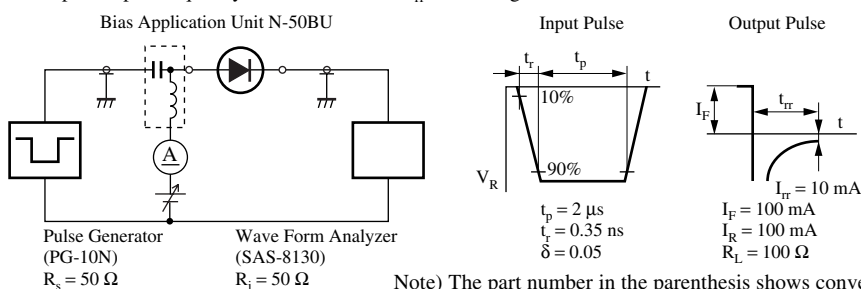
*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

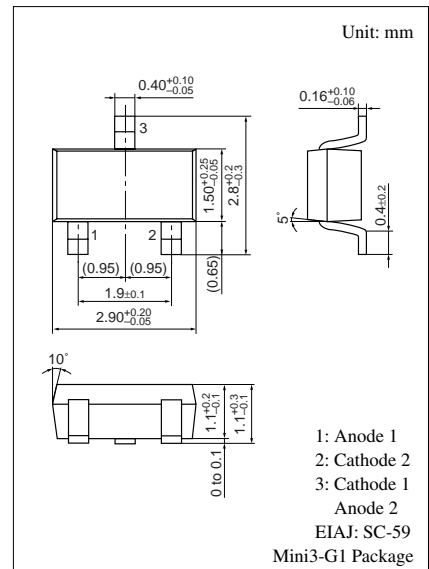
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-------------------------|----------|--|-----|-----|------|---------------|
| Reverse current (DC) | I_R | $V_R = 30$ V | | | 50 | μA |
| Forward voltage (DC) | V_F | $I_F = 200$ mA | | | 0.55 | V |
| Terminal capacitance | C_t | $V_R = 0$ V, $f = 1$ MHz | | 30 | | pF |
| Reverse recovery time * | t_{rr} | $I_F = I_R = 100$ mA $I_{tr} = 10$ mA, $R_L = 100 \Omega$ | | 3 | | ns |

Note) 1. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

2. Rated input/output frequency: 1 GHz 3. *: t_{rr} measuring instrument

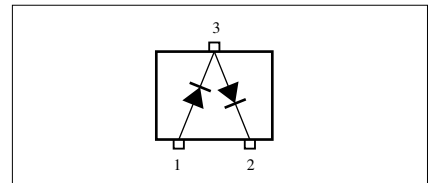


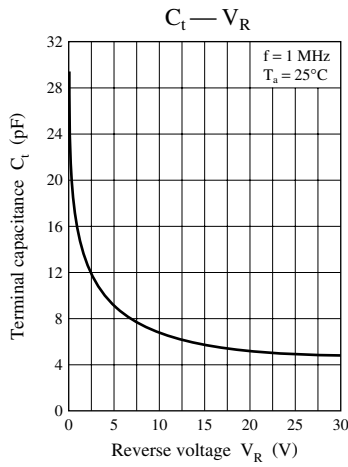
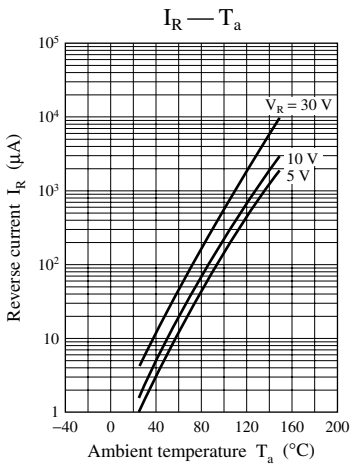
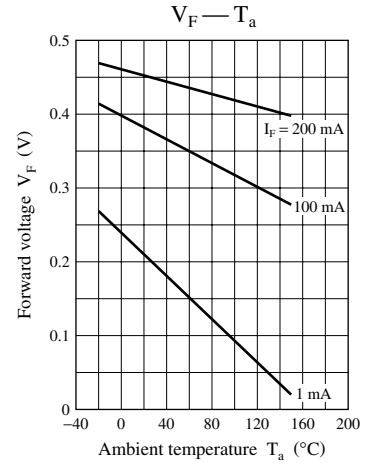
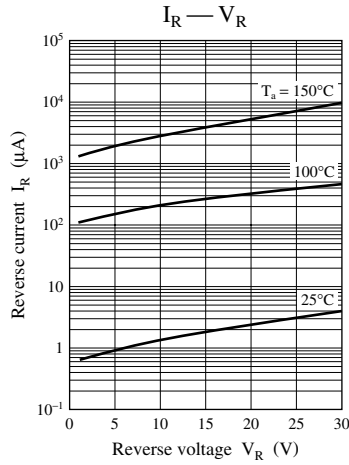
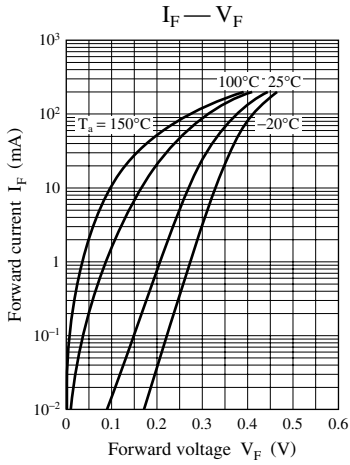
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M3C

Internal Connection





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